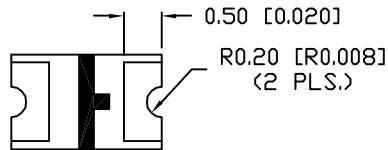
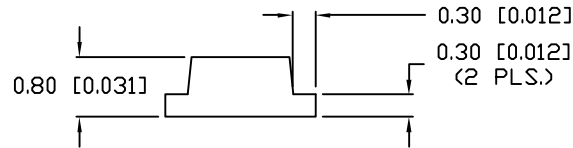
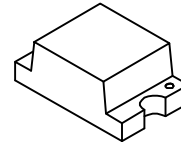
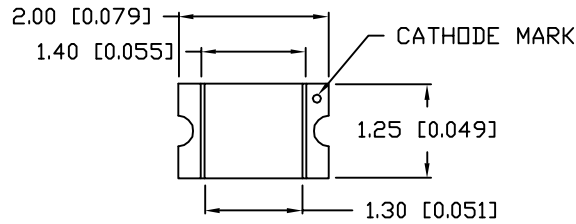


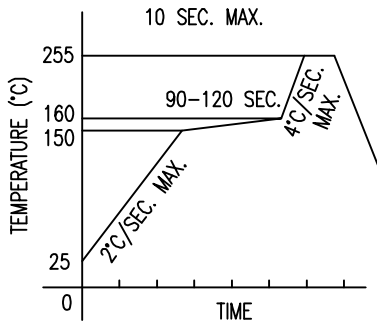
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PART NUMBER
SML-LXT0805UPGW-TR

REV.
C



LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10967.	3.22.04
B	E.C.N. #11248.	8.12.05
C	E.C.N. #11508.	09.30.09

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		525		nm	
FORWARD VOLTAGE		3.5	4.0	V _f	
REVERSE VOLTAGE	5.0			V _r	I _r =100μA
AXIAL INTENSITY	63	130		mcd	I _f =20mA
VIEWING ANGLE		140		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	50	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-25 TO +80	°C
STORAGE TEMP.	-30 TO +85	°C

* t<10μs

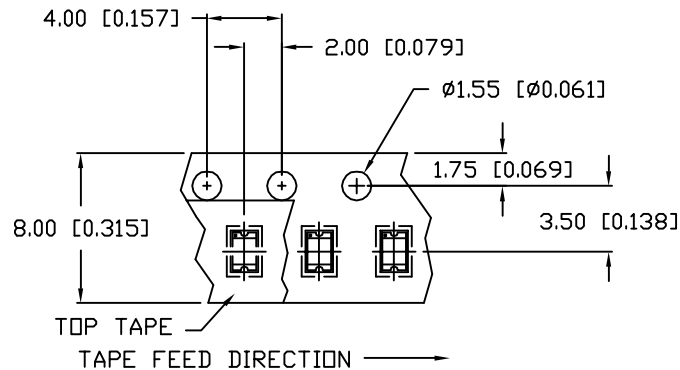
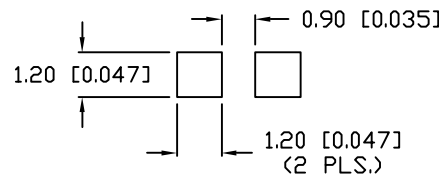
NOTES:

- 4K PER REEL
- CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.



CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 2 STANDARDS

RECOMMENDED SOLDER PAD LAYOUT



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN.= +DECIMAL PRECISION -0.00 MAX.= +0.00 -DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV.	PART NUMBER	CONFIDENTIAL INFORMATION	290 E. HELEN ROAD PALATINE, IL 60067-6976 PHONE: +1.847.359.2790 US WEB: www.lumex.com TW WEB: www.lumex.com.tw		
C	SML-LXT0805UPGW-TR	THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC., THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.			
2.0mm x 1.25mm THIN PCB SURFACE MOUNT, 525nm InGaN GREEN LED, MILKY WHITE DIFFUSED LENS, TAPE AND REEL.		RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.			
		DRAWN BY: CT	CHECKED BY:	APPROVED BY:	DATE: 2.10.03 PAGE: 1 OF 1 SCALE: N/A